

Product Specification

The SGS-ATES Z80 product line is a complete set of micro-computer components, development systems and support software. The Z-80 microcomputer component set includes all of the circuits necessary to build high-performance microcomputer systems with virtually no other logic and a minimum number of low cost standard memory elements.

The Z-80 Parallel I/O (PIO) Interface Controller is a programmable, two port device which provides TTL compatible interfacing between peripheral devices and the Z80-CPU. The Z80-CPU configures the Z80-PIO to interface with standard peripheral devices such as tape punches, printers, keyboards, etc.

Structure

- N-Channel Silicon Gate Depletion Load technology
- 40 Pin DIP
- Single 5 volt supply
- Single phase 5 volt clock
- Two independent 8-bit bidirectional peripheral interface ports with "handshake" data transfer control

Features

- Interrupt driven "handshake" for fast response
- Any one of the following modes of operation may be selected for either port:
 - Byte output
 - Byte input

Byte bidirectional bus (available on Port A only)
Bit Mode

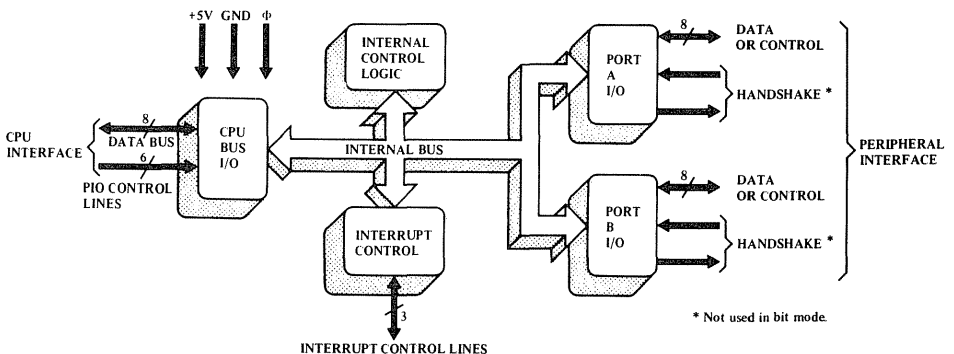
- Programmable interrupts on peripheral status conditions
- Daisy chain priority interrupt logic included to provide for automatic interrupt vectoring without external logic.
- Eight outputs are capable of driving Darlington transistors.
- All inputs and outputs fully TTL compatible.

PIO Architecture

A block diagram of the Z80-PIO is shown in figure 3. The internal structure of the Z80-PIO consists of a Z80-CPU bus interface, internal control logic, Port A I/O logic, Port B I/O logic, and interrupt control logic. A typical application might use Port A as the data transfer channel and Port B for the status and control monitoring.

The Port I/O logic is composed of 6 registers with "handshake" control logic as shown in figure 4. The registers include: an 8-bit input register, an 8-bit output register, a 2-bit mode control register, an 8-bit mask register, an 8-bit input/output select register, and a 2-bit mask control register. The last three registers are used only when the port has been programmed to operate in the bit mode.

Fig. 3 - PIO BLOCK DIAGRAM





Register Description

Mode Control Register—2 bits, loaded by CPU to select the operating mode: byte output, byte input, byte bidirectional bus or bit mode.

Data Output Register—8 bits, permits data to be transferred from the CPU to the peripheral.

Data Input Register—8 bits, accepts data from the peripheral for transfer to the CPU.

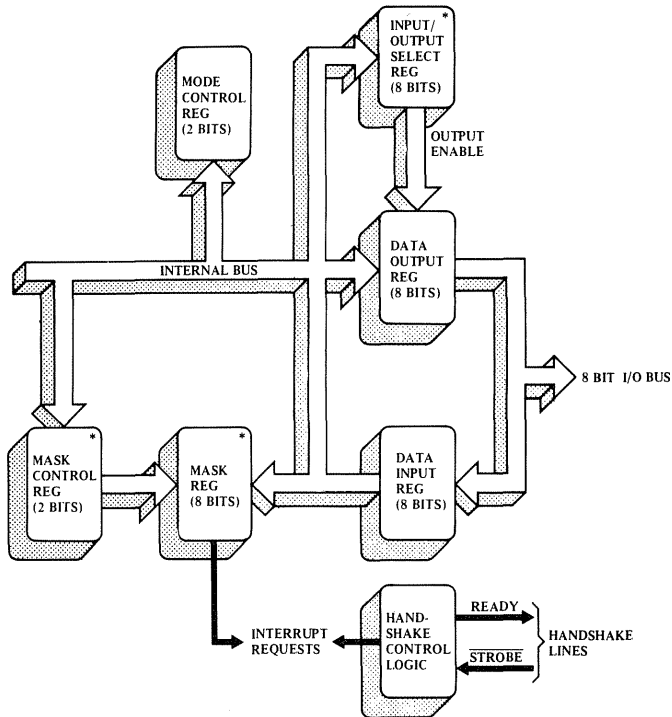
Mask Control Register—2 bits, loaded by the CPU to specify the active state (high or low) of any peripheral device

interface pins that are to be monitored and, if an interrupt should be generated when all unmasked pins are active (AND condition) or, when any unmasked pin is active (OR condition).

Mask Register—8 bits, loaded by the CPU to determine which peripheral device interface pins are to be monitored for the specified status condition.

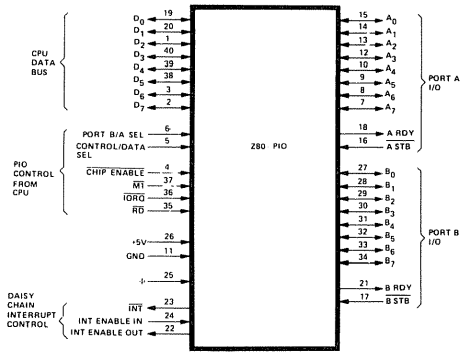
Input/Output Select Register—8 bits, loaded by the CPU to allow any pin to be an output or an input during bit mode operation.

Fig. 4 - A TYPICAL PORT I/O BLOCK DIAGRAM



* Used in the bit mode only to allow generation of an interrupt if the peripheral I/O pins go to the specified state

Z80-PIO Pin Description



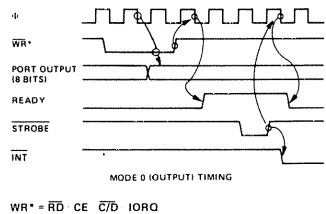
- D_7-D_0 Z80-CPU Data Bus (bidirectional, tristate)
- B/A Sel Port B or A Select (input, active high)
- C/D Sel Control or Data Select (input, active high)
- \overline{CE} Chip Enable (input, active low)
- Φ System Clock (input)

- $\overline{M1}$ Machine Cycle One Signal from CPU (input, active low)
- \overline{IORQ} Input/Output Request from Z80-CPU (input, active low)
- \overline{RD} Read Cycle Status from the Z80-CPU (input, active low)
- \overline{IEI} Interrupt Enable In (input, active high)
- \overline{IEO} Interrupt Enable Out (output, active high). \overline{IEI} and \overline{IEO} form a daisy chain connection for priority interrupt control.
- \overline{INT} Interrupt Request (output, open drain, active low)
- A_0-A_7 Port A Bus (bidirectional, tristate)
- $A\ STB$ Port A Strobe Pulse from Peripheral Device (input, active low)
- $A\ RDY$ Register A Ready (output, active high)
- B_0-B_7 Port B Bus (bidirectional, tristate)
- $B\ STB$ Port B Strobe Pulse from Peripheral Device (input, active low)
- $B\ RDY$ Register B Ready (output, active high)

Timing Waveforms

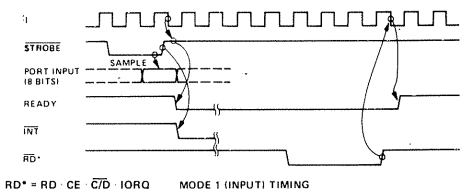
OUTPUT MODE

An output cycle is always started by the execution of an output instruction by the CPU. The \overline{WR} pulse from the CPU latches the data from the CPU data bus into the selected port's output register. The write pulse sets the ready flag after a low going edge of Φ , indicating data is available. Ready stays active until the positive edge of the strobe line is received indicating that data was taken by the peripheral. The positive edge of the strobe pulse generates an \overline{INT} if the interrupt enable flip flop has been set and if this device has the highest priority.



INPUT MODE

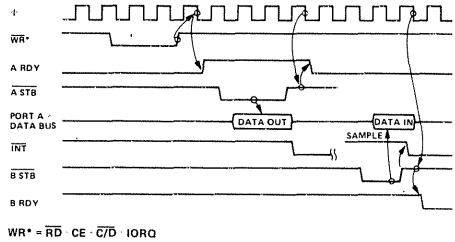
When \overline{STROBE} goes low data is loaded into the selected port input register. The next rising edge of strobe activates \overline{INT} if interrupt enable is set and this is the highest priority requesting device. The following falling edge of Φ resets Ready to an inactive state, indicating that the input register is full and cannot accept any more data until the CPU completes a read. When a read is complete the positive edge of \overline{RD} will set Ready at the next low going transition of Φ . At this time new data can be loaded into the PIO.



Timing Waveforms (continued)

BIDIRECTIONAL MODE

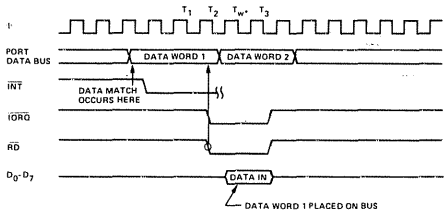
This is a combination of modes 0 and 1 using all four handshake lines and the 8 Port A I/O lines. Port B must be set to the Bit Mode. The Port A handshake lines are used for output control and the Port B lines are used for input control. Data is allowed out onto the Port A bus only when A STB is low. The rising edge of this strobe can be used to latch the data into the peripheral.



BIT MODE

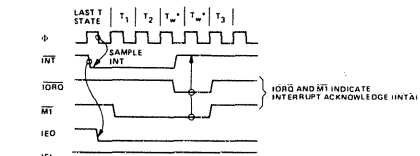
The bit mode does not utilize the handshake signals and a normal port write or port read can be executed at any time. When writing, the data will be latched into the output registers with the same timing as the output mode.

When reading the PIO, the data returned to the CPU will be composed of output register data from those port data lines assigned as outputs and input register data from those port data lines assigned as inputs. The input register will contain data which was present immediately prior to the falling edge of RD. An interrupt will be generated if interrupts from the port are enabled and the data on the port data lines satisfy the logical equation defined by the 8-bit mask and 2-bit mask control registers.



INTERRUPT ACKNOWLEDGE

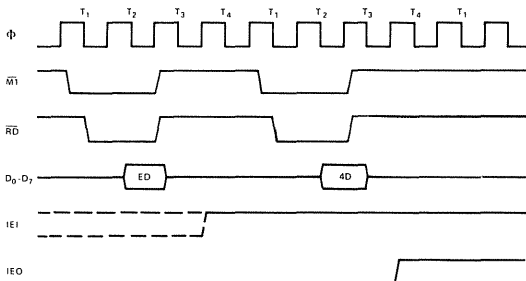
During \overline{MI} time, peripheral controllers are inhibited from changing their interrupt enable status, permitting the \overline{INT} Enable signal to ripple through the daisy chain. The peripheral with IEI high and IEO low during \overline{INTA} will place a preprogrammed 8-bit interrupt vector on the data bus at this time. IEO is held low until a return from interrupt (RETI) instruction is executed by the CPU while IEI is high. The 2-byte RETI instruction is decoded internally by the PIO for this purpose.



RETURN FROM INTERRUPT CYCLE

If a Z80 peripheral device has no interrupt pending and is not under service, then its $IEO=IEI$. If it has an interrupt under service (i.e., it has already interrupted and received an interrupt acknowledge) then its IEO is always low, inhibiting lower priority chips from interrupting. If it has an interrupt pending which has not yet been acknowledged, IEO will be low unless an "ED" is decoded as the first byte of a two byte opcode. In this case, IEO will go high until the next opcode byte is decoded, whereupon it will again go low. If the second byte of the opcode was a "4D" then the opcode was an RETI instruction.

After an "ED" opcode is decoded, only the peripheral device which has interrupted and is currently under service will have its IEI high and its IEO low. This device is the highest priority device in the daisy chain which has received an interrupt acknowledge. All other peripherals have $IEI=IEO$. If the next opcode byte decoded is "4D", this peripheral device will reset its "interrupt under service" condition.



Z80-PIO A.C. Characteristics

TA = 0° C to 70° C, Vcc = +5 V ± 5%, unless otherwise noted

Number	Symbol	Parameter	Min	Max	Unit	Comments
1	TcC	Clock Cycle Time	250	[1]	ns	
2	TcCh	Clock Width (High)	105	2000	ns	
3	TcCL	Clock Width (Low)	105	2000	ns	
4	TIC	Clock Fall Time		30	ns	
5	TrC	Clock Rise Time		30	ns	
6	TsCS(RI)	CE, B/A, C/E to RD, IORQ ↓ Setup Time	50		ns	[6]
7	Th	Any Hold Time for specified Setup Time	0		ns	
8	TsRI(C)	RD, IORQ to Clock ↓ Setup Time	115		ns	
9	TdRI(DO)	RD, IORQ ↓ to Data Out Delay		380	ns	[2]
10	TdRI(DOR)	RD, IORQ ↑ to Data Out Float Delay		110	ns	
11	TsDI(C)	Data In to Clock ↑ Setup Time	50		ns	CL = 50 pF
12	TdIO(DOI)	IORQ ↓ to Data Out Delay (INTA Cycle)	250		ns	[3]
13	TsM1(Cr)	M1 ↓ to Clock ↑ Setup Time	90		ns	
14	TsM1(Cf)	M1 ↑ to Clock ↓ Setup Time (M1 Cycle)	0		ns	
15	TdM1(IEO)	M1 ↓ to IEO ↓ Delay (interrupt immediately preceding M1)		190	ns	
16	TsEI(IEO)	IEI to IORQ ↓ Setup Time (INTA Cycle)	140	190	ns	[5] See Note A
17	TdEI(IEO)	IEI ↓ to IEO ↓ Delay		130	ns	See Note A
18	TdEI(IEOR)	IEI ↑ to IEO ↑ Delay (after ED Decode)		160	ns	[5] CL = 50 pF
19	TsIO(C)	IORQ ↑ to Clock ↓ Setup Time (To Activate READY on Next Clock Cycle)	220		ns	
20	TdC(RDYr)	Clock ↓ to READY ↑ Delay	200		ns	[5] CL = 50 pF
21	TdC(RDYf)	Clock ↓ to READY ↓ Delay	150		ns	[5]
22	TwSTB	STROBE Pulse Width	150 [4]		ns	
23	TsSTB(C)	STROBE ↑ to Clock ↓ Setup Time (To Activate READY on Next Clock Cycle)	200		ns	
24	TdIO(PD)	IORQ ↑ to PORT data stable Delay (Mode 0)		180	ns	[5]
25	TsPD(STB)	PORT DATA to STROBE ↑ Setup Time (Mode 1)	230		ns	
26	TdSTB(PD)	STROBE ↓ to PORT DATA Stable (Mode 2)		210	ns	[5]
27	TdSTB(PDz)	STROBE ↑ to PORT DATA Float Delay (Mode 2)		180	ns	CL = 50 pF
28	TdPD(INT)	PORT DATA Match to INT ↓ Delay (Mode 3)		490	ns	
29	TdSTB(INT)	STROBE ↑ to INT ↓ Delay		440	ns	

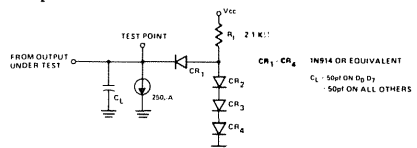
- Notes A 2.5 TcC > (N-2) TdEI (IEOG) + TdM1(IEO) + TsEI(IEO) + TTL Buffer Delay, if any
 B, M1 Must be active for a minimum of 2 clock cycles to reset the PIO
 [1] TcC = TwCh + TwCl + TrC + TIC
 [2] Increase TdRI(DO) by 10 nsec for each 50 pF increase in loading up to 200 pF max
 [3] Increase TdIO(DOT) by 10 nsec for each 60 pF increase in loading up to 200 pF max
 [4] For Mode 2, TwSTB > TsPD(STB)
 [5] Increase these values by 2 nsec for each 10 pF increase in loading up to 100 pF max
 [6] TsCS(RI) may be reduced. However the time subtracted from TsCS(RI) will be added to TdRI(DO)

Capacitance

TA = 25° C, f = 1 MHz

Symbol	Parameter	Max	Unit	Test Condition
C _Φ	Clock Capacitance	10	pF	Unmeasured Pins
C _{IN}	Input Capacitance	5	pF	Returned to Ground
C _{OUT}	Output Capacitance	10	pF	

Output Load circuit



Z80A-PIO A.C. Characteristics

TA = 0° C to 70° C, Vcc = +5 V ± 5%, unless otherwise noted

Number	Symbol	Parameter	Min	Max	Unit	Comments
1	TcC	Clock Cycle Time	400	[1]	ns	
2	TcCh	Clock Width (High)	170	2000	ns	
3	TcCL	Clock Width (Low)	170	2000	ns	
4	TfC	Clock Fall Time		30	ns	
5	TrC	Clock Rise Time		30	ns	
6	TsCS(RI)	\overline{CE} , B/ \overline{A} , C/E to \overline{RD} , \overline{IORQ} ↓ Setup Time	50		ns	[6]
7	Th	Any Hold Time for specified Setup Time	0		ns	
8	TsRI(C)	\overline{RD} , \overline{IORQ} to Clock ↑ Setup Time	115		ns	
9	TdRI(DO)	\overline{RD} , \overline{IORQ} ↓ to Data Out Delay		430	ns	[2]
10	TdRI(DOr)	\overline{RD} , \overline{IORQ} ↑ to Data Out Float Delay		160	ns	
11	TsDI(C)	Data In to Clock ↑ Setup Time	50		ns	CL = 50 pF
12	TdIO(DOI)	\overline{IORQ} ↓ to Data Out Delay (INTA Cycle)	340		ns	[3]
13	TsM1(Cr)	M1 ↓ to Clock ↑ Setup Time	210		ns	
14	TsM1(CI)	M1 ↑ to Clock ↓ Setup Time (M1 Cycle)	0		ns	
15	TdM1(IEO)	M1 ↓ to IEO ↓ Delay (interrupt immediately preceding M1 ↓)		300	ns	[5] See Note A
16	TsEI(IEO)	IEI to \overline{IORQ} ↓ Setup Time (INTA Cycle)	140		ns	See Note A
17	TdEI(IEO)	IEI ↓ to IEO ↓ Delay		190	ns	[5] CL = 50 pF
18	TdEI(IEOr)	IEI ↑ to IEO ↑ Delay (after ED Decode)		210	ns	[5]
19	TsIO(C)	\overline{IORQ} ↑ to Clock ↓ Setup Time (To Activate READY on Next Clock Cycle)	220		ns	
20	TdC(RDYr)	Clock ↓ to READY ↑ Delay	200		ns	[5] CL = 50 pF
21	TdC(RDYf)	Clock ↓ to READY ↓ Delay	150		ns	[5]
22	TwSTB	STROBE Pulse Width	150 [4]		ns	
23	TsSTB(C)	STROBE ↑ to Clock ↓ Setup Time (To Activate READY on Next Clock Cycle)	220		ns	
24	TdIO(PD)	\overline{IORQ} ↑ to PORT data stable Delay (Mode 0)		200	ns	[5]
25	TsPD(STB)	PORT DATA to STROBE ↑ Setup Time (Mode 1)	260		ns	
26	TdSTB(PD)	STROBE ↓ to PORT DATA Stable (Mode 2)		230	ns	[5]
27	TdSTB(PDz)	STROBE ↑ to PORT DATA Float Delay (Mode 2)		200	ns	CL = 50 pF
28	TdPD(INT)	PORT DATA Match to INT ↓ Delay (Mode 3)		540	ns	
29	TdSTB(INT)	STROBE ↑ to INT ↓ Delay		490	ns	

Notes A 2.5 TcC > (N-2) TdEI(IEOG) + TdM1(IEO) + TsEI(IEO) + TTL Buffer Delay, if any

B M1 Must be active for a minimum of 2 clock cycles to reset the PIO

[1] TcC = TwCh + TwCl + TrC + TfC

[2] Increase TdRI(DO) by 10 nsec for each 50 pF increase in loading up to 200 pF max

[3] Increase TdIO(DO) by 10 nsec for each 60 pF increase in loading up to 200 pF max

[4] For Mode 2 TwSTB > TsPD(STB)

[5] Increase these values by 2 nsec for each 10 pF increase in loading up to 100 pF max

[6] TsCS(RI) may be reduced. However the time subtracted from TsCS(RI) will be added to TdRI(DO)

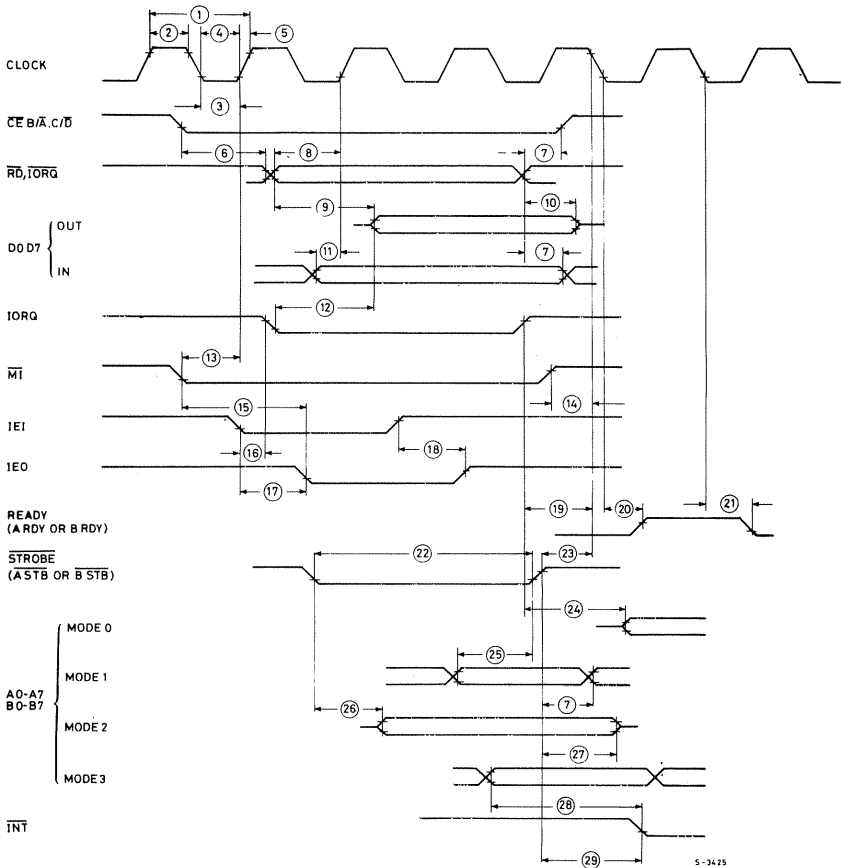


Z 80-PIO
Z 80A-PIO

A.C. Timing Diagram

Timing measurements are made at the following voltages,
unless otherwise specified:

	"1"	"0"
CLOCK	V _{CC} -0.6V	0.45V
OUTPUT	2V	0.8V
INPUT	2V	0.8V
FLOAT	ΔV	±0.5V



S-3425



Absolute Maximum Ratings

Temperature Under Bias Storage Temperature Voltage On Any Pin with Respect to Ground Power Dissipation	Specified operating range -65°C to +150°C -0.3V to +7V 0.6W
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Note: All AC and DC characteristics remain the same for the military grade parts except I_{CC} .
 $I_{CC} = 130 \text{ mA}$

*** Comment**

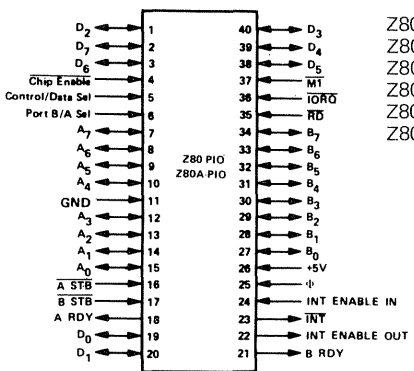
Stresses above those listed under "Absolute Maximum Rating" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other condition above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Z80-PIO and Z80A-PIO D.C. Characteristics

$T_A = 0^\circ\text{C}$ to 70°C , $V_{CC} = +5\text{V} \pm 5\%$, unless otherwise noted

Symbol	Parameter	Min.	Max.	Unit	Test Condition
V_{ILC}	Clock Input Low Voltage	-0.3	0.45	V	$I_{OL} = 2.0 \text{ mA}$ $I_{OH} = 250 \mu\text{A}$
V_{IHC}	Clock Input High Voltage	$V_{CC}-0.6$	$V_{CC}+0.3$	V	
V_{IL}	Input Low Voltage	-0.3	0.8	V	
V_{IH}	Input High Voltage	2	V_{CC}	V	
V_{OL}	Output Low Voltage		0.4	V	
V_{OH}	Output High Voltage	2.4		V	
I_{CC}	Power Supply Current		70	mA	
I_{LI}	Input Leakage Current		10	μA	$V_{IN} = 0 \text{ to } V_{CC}$
I_{LOH}	Tri-State Output Leakage Current in Float		10	μA	$V_{OUT} = 2.4 \text{ to } V_{CC}$
I_{LOL}	Tri-State Output Leakage Current in Float		-10	μA	$V_{OUT} = 0.4 \text{ V}$
I_{LD}	Data Bus Leakage Current in Input Mode		± 10	μA	$0 \leq V_{IN} \leq V_{CC}$
I_{OHD}	Darlington Drive Current	-1.5		mA	$V_{OH} = 1.5 \text{ V}$
					Port B Only

PIN CONNECTIONS

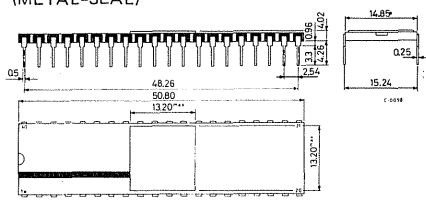


ORDERING NUMBERS:

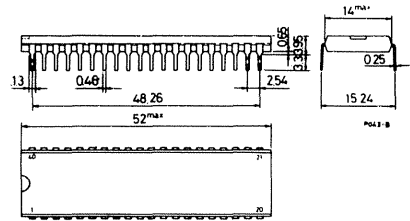
- Z80PIO D1 for dual in-line ceramic package (metal-seal)
- Z80PIO B1 for dual in-line plastic package
- Z80APIO D1 for dual in-line ceramic package (metal-seal)
- Z80APIO B1 for dual in-line plastic package
- Z80PIO F1 for dual in-line ceramic package (frit-seal)
- Z80APIO F1 for dual in-line ceramic package (frit-seal)

MECHANICAL DATA (dimension in mm)

40-PIN CERAMIC DUAL IN-LINE PACKAGE (METAL-SEAL)



40-PIN PLASTIC DUAL IN-LINE PACKAGE



40-PIN CERAMIC DUAL IN-LINE PACKAGE (FRIT-SEAL)

